

Pure Silver Sintering Paste

Parameter	Test/Measure	DN-1206QB	DN-1206CR1	DN-1208R1	DN-1301B
Curing Temp	degC	200	200	200	175
Viscosity @25deg.C	E-viscometer@5rpm	11,000	10,800	12,000	13,000
Thixotropic Index @25deg.C	0.5rpm/5rpm	5.5	6.1	3.0	5.5
Open Time (for 1*1 mm ² die size)	Hour	6	4	6	6
Volume Resistance	Ohm.cm	5.5*10 ⁻⁶	9.0*10 ⁻⁶	3.9*10 ⁻⁶	2.5*10 ⁻⁶
Thermal Conductivity	W/mk	140	150	230	130
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	35	32	100	32
	On Cu PCB (Mpa)	15	32	12	25
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	15	17	100	19
	On Cu PCB (Mpa)	10	10	12	12
Storage Modulus@25 Deg.C	GPa	15.1	13	18	18
CTE	ppm	40	30	15.2	51
Product Benefit		1.Good Reliability 2.Long open time	1.For printing & dispensing 2.Chemical resistance	1.Extreme high TC 2.Great adhesion on Ag & Au finish	1. Good workability 2. Long open time 3. Less CTE mismatch